



Material Content Data Sheet



Sales Product Name		BSC067N06LS3 G		Issued		19. July 2018		
MA#		MA001171250						
Package		PG-TDSON-8-5		Weight*		119.40 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.835	1.54	1.54	15368	15368
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		317	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.62	31.66	316265	316677
wire	non noble metal	copper	7440-50-8	0.060	0.05	0.05	501	501
encapsulation	organic material	carbon black	1333-86-4	0.085	0.07		713	
	plastics	epoxy resin	-	6.046	5.06		50640	
	inorganic material	silicondioxide	60676-86-0	36.449	30.53	35.66	305269	356622
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12158	12158
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1386	1386
solder	noble metal	silver	7440-22-4	0.046	0.04		385	
	non noble metal	tin	7440-31-5	0.037	0.03		308	
	non noble metal	lead	7439-92-1	1.758	1.47	1.54	14721	15414
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.48	9.49	94809	94932
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		187	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.67	18.70	186699	186942
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com